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Notification Number:	20260730000.0	Notification Issued	August 06, 2026
Datasheet for SN74LVC240A, SNx4LVC541A, SN74LVC540A, SN74LVC244A, SN74LVCZ240A, SN74LVCZ244A			
Change Type(s)	Data Sheet/Electrical Specification		
ZVEI ID	SEM-DS-02		

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



SN74LVC240A

SCAS293M – JANUARY 1993 – REVISED JUNE 2026

Changes from July 1, 2014 to June 25, 2026 (from Revision L (July 2014) to Revision M (June 2026))

	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document	1
• Moved ESD ratings to <i>ESD Ratings</i> table.....	1
• Updated latch-up ratings to latest standards.....	1
• Updated <i>Device Information</i> format and included package size.....	1
• Updated <i>Simplified Schematic</i>	1
• Updated <i>Applications</i>	1
• Added DGS and RKS package information.....	1
• Added DGS and RKS package information.....	2
• Added <i>ESD Ratings</i> table.....	4
• Changed Junction-to-ambient thermal resistance value for PW package from: 102.5°C/W to: 120.3°C/W	5
• Changed Junction-to-case (top) thermal resistance value for PW package from: 35.9°C/W to: 62.5°C/W.....	5
• Changed Junction-to-board thermal resistance value for PW package from: 53.5°C/W to: 82.4°C/W.....	5
• Changed Junction-to-top characterization value for PW package from: 2.2°C/W to: 16.0°C/W.....	5
• Changed Junction-to-board characterization value for PW package from: 52.9°C/W to: 81.5°C/W.....	5
• Added DW, DB and NS package Thermal Information table.....	5
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately".....	13
• Updated <i>Detailed Description, Application and Implementation</i> and <i>Device Documentation</i> sections.....	15



SN54LVC541A, SN74LVC541A

SCAS298O – JANUARY 1993 – REVISED JUNE 2026

Changes from June 1, 2014 to June 17, 2026 (from Revision N (June 2014) to Revision O (June 2026))

	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Moved ESD ratings to <i>ESD Ratings</i> table.....	1
• Updated latch-up ratings to latest standards.....	1
• Updated <i>Device Information</i> format and included package size.....	1
• Updated <i>Simplified Schematic</i>	1
• Updated <i>Applications</i>	1
• Added DGS and RKS package information.....	1
• Changed R8JA for DB package from: 112.1°C/W to: 121.7°C/W.....	6
• Changed R8JC(top) for DB package from: 73.6°C/W to: 86.8°C/W.....	6

• Changed Ψ_{JT} for DB package from: 67.3°C/W to: 87.8°C/W.....	6
• Changed Ψ_{JB} for DB package from: 33.3°C/W to: 44.7°C/W.....	6
• Changed $R_{\theta JC(bot)}$ for DB package from: 66.9°C/W to: 87°C/W.....	6
• Changed $R_{\theta JA}$ for DW package from: 99.4°C/W to: 114.8°C/W.....	6
• Changed $R_{\theta JC(top)}$ for DW package from: 66.9°C/W to: 84.1°C/W.....	6
• Changed Ψ_{JT} for DW package from: 66.9°C/W to: 88.8°C/W.....	6
• Changed Ψ_{JB} for DW package from: 33.8°C/W to: 55.8°C/W.....	6
• Changed $R_{\theta JC(bot)}$ for DW package from: 66.5°C/W to: 87.8°C/W.....	6
• Changed $R_{\theta JA}$ for NS package from: 90.3°C/W to: 116.3°C/W.....	6
• Changed $R_{\theta JC(top)}$ for NS package from: 56.6°C/W to: 82.4°C/W.....	6
• Changed Ψ_{JT} for NS package from: 57.8°C/W to: 86.2°C/W.....	6
• Changed Ψ_{JB} for NS package from: 28.7°C/W to: 43.9°C/W.....	6
• Changed $R_{\theta JC(bot)}$ for NS package from: 57.4°C/W to: 85.5°C/W.....	6
• Changed $R_{\theta JA}$ for PW package from: 100.8°C/W to: 120.3°C/W.....	6
• Changed $R_{\theta JC(top)}$ for PW package from: 35.2°C/W to: 62.5°C/W.....	6
• Changed Ψ_{JT} for PW package from: 51.8°C/W to: 82.4°C/W.....	6
• Changed Ψ_{JB} for PW package from: 2.2°C/W to: 16°C/W.....	6
• Changed $R_{\theta JC(bot)}$ for PW package from: 51.2°C/W to: 81.5°C/W.....	6
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately".....	14



SN74LVC540A

SCAS2970 – JANUARY 1993 – REVISED JUNE 2026

Changes from May 1, 2014 to June 25, 2026 (from Revision N (May 2014) to Revision O (June 2026))

	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Moved ESD ratings to <i>ESD Ratings</i> table.....	1
• Updated latch-up ratings to latest standards.....	1
• Deleted military disclaimers.....	1
• Updated <i>Device Information</i> format and included package size.....	1
• Updated <i>Simplified Schematic</i>	1
• Updated <i>Applications</i>	1
• Added DGS and RKS package information.....	1
• Added DGS and RKS packages to <i>Thermal Information</i> table.....	5
• Changed $R_{\theta JA}$ for DW package from: 88.3°C/W to: 114.8°C/W.....	5
• Changed $R_{\theta JC(top)}$ for DW package from: 51.1°C/W to: 84.1°C/W.....	5
• Changed Ψ_{JT} for DW package from: 50.9°C/W to: 88.8°C/W.....	5
• Changed Ψ_{JB} for DW package from: 20°C/W to: 55.8°C/W.....	5
• Changed $R_{\theta JC(bot)}$ for DW package from: 50.5°C/W to: 87.8°C/W.....	5
• Changed $R_{\theta JA}$ for PW package from: 102.5°C/W to: 120.3°C/W.....	5
• Changed $R_{\theta JC(top)}$ for PW package from: 35.9°C/W to: 62.5°C/W.....	5
• Changed Ψ_{JT} for PW package from: 53.5°C/W to: 82.4°C/W.....	5
• Changed Ψ_{JB} for PW package from: 2.2°C/W to: 16°C/W.....	5
• Changed $R_{\theta JC(bot)}$ for PW package from: 52.9°C/W to: 81.5°C/W.....	5
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately".....	13



SN74LVC244A

SCAS414AG – NOVEMBER 1992 – REVISED JUNE 2026

Changes from February 2, 2026 to June 26, 2026 (from Revision AF (February 2026) to Revision AG (June 2026))

	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed R θ JA for DB package from: 108.1°C/W to: 121.7°C/W.....	6
• Changed R θ JC(top) for DB package from: 70.2°C/W to: 86.8°C/W.....	6
• Changed Ψ JT for DB package from: 63.3°C/W to: 87.8°C/W.....	6
• Changed Ψ JB for DB package from: 30.6°C/W to: 44.7°C/W.....	6
• Changed R θ JA for DW package from: 90.9°C/W to: 114.8°C/W.....	6
• Changed R θ JC(top) for DW package from: 55.3°C/W to: 84.1°C/W.....	6
• Changed Ψ JT for DW package from: 58.8°C/W to: 88.8°C/W.....	6
• Changed Ψ JB for DW package from: 29.1°C/W to: 55.8°C/W.....	6
• Changed R θ JA for NS package from: 90.1°C/W to: 116.3°C/W.....	6
• Changed R θ JC(top) for NS package from: 56.4°C/W to: 82.4°C/W.....	6
• Changed Ψ JT for NS package from: 57.7°C/W to: 86.2°C/W.....	6
• Changed Ψ JB for NS package from: 28.4°C/W to: 43.9°C/W.....	6
• Changed R θ JA for PW package from: 114.7°C/W to: 120.3°C/W.....	6
• Changed R θ JC(top) for PW package from: 48.4°C/W to: 62.5°C/W.....	6
• Changed Ψ JT for PW package from: 65.6°C/W to: 82.4°C/W.....	6
• Changed Ψ JB for PW package from: 6.8°C/W to: 16°C/W.....	6
• Changed R θ JA for RGY package from: 50.3°C/W to: 82.84°C/W.....	6
• Changed R θ JC(top) for RGY package from: 58.4°C/W to: 88.73°C/W.....	6
• Changed Ψ JT for RGY package from: 28.3°C/W to: 56.81°C/W.....	6
• Changed Ψ JB for RGY package from: 4.9°C/W to: 32.37°C/W.....	6
• Changed R θ JC(bot) for RGY package from: 28.4°C/W to: 56.62°C/W.....	6



SN74LVCZ240A

SCES273I – JUNE 1999 – REVISED JUNE 2026

Changes from April 1, 2005 to June 24, 2026 (from Revision H (April 2005) to Revision I (June 2026))

	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Moved ESD ratings to <i>ESD Ratings</i> table.....	1
• Updated latch-up ratings to latest standards.....	1
• Changed R θ JA for DW package from: 58°C/W to: 114.8°C/W.....	5
• Changed R θ JA for NS package from: 60°C/W to: 116.3°C/W.....	5
• Changed R θ JA for PW package from: 83°C/W to: 120.3°C/W.....	5
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately".....	14

Changes from October 1, 2014 to June 1, 2026 (from Revision I (October 2014) to Revision J (June 2026))

	Page
• Add RKS package options.....	1
• Moved T_{stg} to <i>Absolute Maximum Ratings</i> table.....	4
• Change <i>Handling Ratings</i> to <i>ESD Ratings</i>	4
• Changed Junction-to-ambient thermal resistance value for PW package from: 103.5°C/W to: 120.3°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for PW package from: 37.9°C/W to: 62.5°C/W.....	5
• Changed Junction-to-board characterization value for PW package from: 54.5°C/W to: 82.4°C/W.....	5
• Changed Junction-to-top characterization value for PW package from: 3.3°C/W to: 16°C/W.....	5
• Changed Junction-to-board characterization value for PW package from: 53.9°C/W to: 81.5°C/W.....	5
• Updated <i>Overview</i> , <i>Application and Implementation</i> , <i>Device</i> and <i>Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	7
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately"	12

The datasheet number will be changing.

Device Family	Change From:	Change To:
SN74LVC240A	SCAS293L	SCAS293M
SNx4LVC541A	SCAS298N	SCAS298O
SN74LVC540A	SCAS297N	SCAS297O
SN74LVC244A	SCAS414AF	SCAS414AG
SN74LVCZ240A	SCES273H	SCES273I
SN74LVCZ244A	SCES274I	SCES274J

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/SN74LVC240A>

<http://www.ti.com/product/SN54LVC541A>

<http://www.ti.com/product/SN74LVC540A>

<http://www.ti.com/product/SN74LVC244A>

<http://www.ti.com/product/SN74LVCZ240A>

<http://www.ti.com/product/SN74LVCZ244A>

Reason for Change:	To accurately reflect device characteristics
Anticipated impact on Form, Fit, Function, Quality or Reliability:	No anticipated impact
Changes to product identification resulting from this PCN:	None

Products Affected:

SN74LVC240ADGVRG4	SN74LVC244APWTG4	SN74LVC244ARWPR
SN74LVC240ADGVRG4.B	SN74LVC244ARGYR	SN74LVC244ARWPR.A
SN74LVC240ADW	SN74LVC244ARGYR.A	SN74LVC540ADB
SN74LVC240APW	SN74LVC540ADGVR.B	SN74LVC540ADW
SN74LVC240APWRG4.B	SN74LVC540APWR.A	SN74LVC540APWT.B
SN74LVC244ADB	SN74LVC541ADGVR.B	SN74LVC541APW-P.B
SN74LVC244APWG4	SN74LVC541ADGVRE4	SN74LVC541APWRG4
SN74LVC244APWR.A	SN74LVC541ANS.B	SN74LVCZ244APW.B
SN74LVC541ADB	SN74LVCZ240ANSR.B	SN74LVC240ADGVR
SN74LVC541ADB.B	SN74LVCZ244ADBR	SN74LVC240ANS.B
SN74LVC541ADGVRG4	SN74LVCZ244APWRG4.B	SN74LVC240ANSR.B
SN74LVC541ADW.B	SN74LVC240ADW.B	SN74LVC240APWR
SN74LVC541APWR.A	SN74LVC244ADGVR	SN74LVC240APWRG4.A
SN74LVC541AQPWRCT.B	SN74LVC244ADGVRG4	SN74LVC240APWT.B
SN74LVC541ARGYR	SN74LVC244ADWG4	SN74LVC244ADWE4
SN74LVC541ARGYR.B	SN74LVC244AN.B	SN74LVC244APW.B
SN74LVCZ240APW.B	SN74LVC244ANS	SN74LVC244APWRG3.A
SN74LVCZ244ADBR.B	SN74LVC244APW-P.B	SN74LVC244ARWPR.B
SN74LVCZ244ANSR.B	SN74LVC244APWR.B	SN74LVC244ARWPRG4.A
SN74LVCZ244APW	SN74LVC244APWRE4	SN74LVC540ADGVR
SN74LVCZ244APWR.B	SN74LVC244APWTE4	SN74LVC540ANS.B
SN74LVC240APWRE4	SN74LVC540ADBRG4.B	SN74LVC540APWR
SN74LVC240APWRG4	SN74LVC540ADGSR	SN74LVC541ANS
SN74LVC244ADGVR.B	SN74LVC540ADWG4	SN74LVC541APWR.B
SN74LVC244ADGVRG4.B	SN74LVC540ANSR.B	SN74LVC541AQPWRCT
SN74LVC244AN	SN74LVC540APWT	SN74LVCZ240APWR.B
SN74LVC244APW-P	SN74LVC541APW.B	SN74LVCZ244APWR.A
SN74LVC244APWRG3	SN74LVC541APWR	SN74LVCZ244APWT.B
SN74LVC244AQPWRNS	SN74LVC541APWRG4.A	SN74LVC240ANSR
SN74LVC244AQPWRNS.A	SN74LVC541APWRG4.B	SN74LVC244ADB.B
SN74LVC244ARGYR.B	SN74LVC541ARGYR.A	SN74LVC244ADW
SN74LVC244ARKSR	SN74LVC240ADBR	SN74LVC244ANS.B
SN74LVC244ARWPRG4	SN74LVC240ADGSR	SN74LVC244APWE4
SN74LVC540APW	SN74LVC240APW.B	SN74LVC244APWR
SN74LVC540APW.B	SN74LVC240APWR.A	SN74LVC244APWR-P
SN74LVC540APWRE4	SN74LVC244APWRG4.A	SN74LVC244APWRG3.B
SN74LVC541ADWG4	SN74LVC244ARWPRG4.B	SN74LVC244APWRG4.B
SN74LVC541ANS4	SN74LVC540ADB.B	SN74LVC244AQPWRNS.B
SN74LVC541ANS4.B	SN74LVC540ADBR	SN74LVC244ARGYRG4
SN74LVC541APW-P	SN74LVC540ADBRG4	SN74LVC540ADBR.B
SN74LVC541APWRE4	SN74LVC540ADW.B	SN74LVC540ANS
SN74LVCZ240ADW.B	SN74LVC540ANSR	SN74LVC540APWR.B
SN74LVCZ240ANSR	SN74LVC540APWRG4	SN74LVC541ADGSR
SN74LVCZ244ANSR	SN74LVC541APW	SN74LVC541ADGVR
SN74LVCZ244APWT	SN74LVC541APWR-P	SN74LVC541ADW
SN74LVC240ADBR.B	SN74LVC541APWT	SN74LVC541ADWG4.B
SN74LVC240ADGVR.B	SN74LVC541APWT.B	SN74LVC541APWG4
SN74LVC240ANS	SN74LVC541ARGYRG4	SN74LVC541APWR-P.B
SN74LVC240APWG4	SN74LVCZ240APW	SN74LVCZ240ADW
SN74LVC240APWR.B	SN74LVCZ240APWR	SN74LVCZ240APWR.A
SN74LVC240APWT	SN74LVCZ244ADGSR	SN74LVCZ244ADWR
SN74LVC244ADW.B	SN74LVCZ244ADWR.B	SN74LVCZ244APWR
SN74LVC244APWR-P.B	SN74LVC244ADGSR	SN74LVCZ244APWRG4
SN74LVC244APWT	SN74LVC244APW	SN74LVCZ244APWRG4.A
SN74LVC244APWT.B	SN74LVC244APWRG4	

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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